



Sir:

PATENT Customer No. 22,852 Attorney Docket No. 04329.2107-03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
Keiichi SASAKI et al.) Group Art Unit: 2823
Application No.: 10/646,703) Examiner: Brewster, William M.
Filed: August 25, 2003)
For: PASTE INCLUDING A MIXTURE OF POWDERS, CONNECTION PLUG, BURYING METHOD, AND SEMICONDUCTOR DEVICE MANUFACTURING METHOD))))
Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450	

RESPONSE TO RESTRICTION REQUIREMENT

In the Office Action dated October 5, 2004, the period for response to which extends through November 5, 2004, the Examiner required restriction under 35 U.S.C. § 121 between the following groups:

Group I, claims 1-3, characterized by the Examiner as drawn to an electrically conductive paste containing metals; and

Group II, claims 5-7, 9-12, and 25-30, characterized by the Examiner as drawn to a method of forming interconnects.

Applicants provisionally elect to prosecute Group II, including claims 5-7, 9-12, and 25-30, without traverse.

Please grant any extensions of time required to enter this response and charge any additional required fees to our deposit account 06-0916.

Respectfully submitted,

FINNEGAN, HENDERSON, FARABOW, GARRETT & DUNNER, L.L.P.

Dated: October 29, 2004

Qingyu Yin

*With limited recognition under 37 C.F.R. § 10.9(b)